

1.1 Scope.

This specification covers the detail requirements for a high speed, low power, unity-gain stable operational amplifier.

1.2 Part Number.

The complete part number per Table 1 of this specification is as follows:

Device	Part Number
-1	AD847SQ/883B

1.2.3 Case Outline.

See Appendix 1 of General Specification ADI-M-1000: package outline: Q-8.

1.3 Absolute Maximum Ratings. ($T_A = +25^\circ\text{C}$ unless otherwise noted)

Supply Voltage	$\pm 18\text{ V}$
Internal Power Dissipation ¹	1.1 W
Input Common-Mode Voltage, Max Safe	$\pm V_S$
Differential Input Voltage	$\pm 6\text{ V}$
Rated Operating Temperature Range	-55°C to $+125^\circ\text{C}$
Storage Temperature Range	-65°C to $+150^\circ\text{C}$
Lead Temperature (Soldering 60 sec)	$+300^\circ\text{C}$

NOTE

¹Maximum internal power dissipation is specified so the T_J does not exceed $+175^\circ\text{C}$ at an ambient temperature of $+25^\circ\text{C}$. Derates at $7.3\text{ mW}/^\circ\text{C}$.

1.5 Thermal Characteristics.

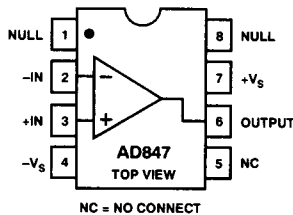
Thermal Resistance $\theta_{JA} = 110^\circ\text{C}/\text{W}$
 $\theta_{JC} = 30^\circ\text{C}/\text{W}$

AD847—SPECIFICATIONS

Table 1.

Test	Symbol	Device	Sub Group 1	Sub Group 2, 3	V _S	Test Conditions	Unit
Input Offset Voltage	V _{OS}	-1	1	4	±5 V		±mV max
Input Bias Current	I _B	-1	5	7.5	±5 V, ±15 V	V _{CM} = 0 V	±μA max
Input Offset Current	I _{OS}	-1	0.3	0.4	±5 V, ±15 V		±μA max
Open Loop Gain	A _{OL}	-1	2	1	±5 V	V _{OUT} = ±2.5 V, R _{LOAD} = 500 Ω	V/mV min
		-1	3	1.5	±15 V	V _{OUT} = ±10 V, R _{LOAD} = 1 kΩ	V/mV min
Common-Mode Rejection Ratio	CMRR	-1	80	75	±5 V	V _{CM} = ±2.5 V	dB min
		-1	80	75	±15 V	V _{CM} = ±12 V	
Output Voltage Swing	V _{OUT}	-1	3		±5 V	R _{LOAD} = 500 Ω	±V min
		-1	2.5		±5 V	R _{LOAD} = 150 Ω	±V min
		-1	12		±15 V	R _{LOAD} = 1 kΩ	±V min
		-1	10		±15 V	R _{LOAD} = 500 Ω	±V min
Power Supply Rejection	PSRR	-1	75	72		V _S = ±5 V to ±15 V	dB min
Power Supply Current	I _Q	-1	5.7	7.8	±5 V	V _{OUT} = 0 V	mA max
		-1	6.3	8.4	±15 V	V _{OUT} = 0 V	

3.2.1 Functional Block Diagram and Terminal Assignments.



3.2.4 Microcircuit Technology Group.

This microcircuit is covered by technology group (85).

4.2.1 Life Test/Burn-in Circuit.

Steady state life test is per MIL-STD-883 Method 1005. Burn-in is per MIL-STD-883 Method 1015 test condition (B).

